



Material Content Data Sheet



Halogen-Free

Sales Product Name IPD78CN10N G

Issued

17. February 2022

MA# MA005699212

Package PG-TO252-3-313

Weight*

317.69 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.177	0.37	0.37	3704	3704
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		464	
	non noble metal	copper	7440-50-8	147.096	46.30	46.36	463020	463623
wire	non noble metal	aluminium	7429-90-5	0.679	0.21	0.21	2137	2137
encapsulation	inorganic material	zinc oxide	1314-13-2	1.424	0.45		4482	
	miscellaneous	miscellaneous	-	7.119	2.24		22408	
	plastics	epoxy resin	-	21.357	6.72		67225	
	inorganic material	silicon dioxide	60676-86-0	112.478	35.41	44.82	354052	448167
lead finish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11773	11773
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4471	4482
solder	non noble metal	tin	7440-31-5	0.036	0.01		113	
	noble metal	silver	7440-22-4	0.045	0.01		142	
	non noble metal	lead	7439-92-1	1.720	0.54	0.56	5415	5670
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.04	6.05	60366	60444
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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